

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of claims:

Claim 1 (Currently Amended): An absolute humidity sensor comprising:
a substrate having a cavity;
a membrane formed on the substrate;
a resistor formed on the membrane;
electrode pads formed on the membrane, for electrically connecting with
the resistor; and

a passivation film formed on an entire surface of the resistor to cover the
resistor[.]; and

a thermal conductive film formed on a region of the passivation film
where the resistor is formed.

Claim 2 (Original): The absolute humidity sensor of claim 1, wherein the
membrane is formed of any one of SiO₂, Si₃N₄, SiO_xN_y, and SiO₂/Si₃N₄/SiO₂.

Claim 3 (Original): The absolute humidity sensor of claim 1, wherein the
resistor is formed of one or more of Ti, Pt, Ni, Ni-Cr, and VO₂.

Claim 4 (Original): The absolute humidity sensor of claim 1, wherein the passivation film is formed of any one of SiO₂, Si₃N₄, SiO_xN_y, phosphor silicate glass (PSG,) and polyimide.

Claim 5 (Cancelled)

Claim 6 (Currently Amended): The absolute humidity sensor of claim 5,
1, wherein the thermal conductive film is formed ~~on~~ of any one of Al and Au.

Claim 7 (Currently Amended): An absolute humidity sensor comprising:
A substrate having a first cavity and a second cavity in a predetermined region;
a membrane formed on the substrate;
a humidity sensing element formed on the membrane where the first cavity is formed, for detecting humidity exposed to the air, having a variable resistance value depending on the detected humidity; and
a temperature compensating element formed on the membrane where the second cavity is formed, for compensating for the resistance value of the humidity sensing element[.] and
a thermal conductive film formed on a region of a passivation film where
a resistor is formed.

Claim 8 (Original): The absolute humidity sensor of claim 7, wherein the humidity sensing element and the temperature compensating element include:

a resistor formed on the membrane;

electrode pads formed on the membrane, for electrically connecting with the resistor; and

a passivation film formed on an entire surface of the resistor to cover the resistor.

Claim 9 (Original): The absolute humidity sensor of claim 8, wherein the membrane is formed of any one of SiO₂, Si₃N₄, SiO_xN_y, and SiO₂/Si₃N₄/SiO₂

Claim 10 (Original): The absolute humidity sensor of claim 8, wherein the resistor is formed of one or more of Ti, Pt, Ni, Ni-Cr, and VO₂.

Claim 11 (original): The absolute humidity sensor of claim 8, wherein the passivation film is formed of any one of SiO₂, Si₃N₄, SiO_xN_y, phosphor silicate glass (PSG) and polyimide.

Claim 12 (Cancelled)

Claim 13. (Currently Amended): The absolute humidity sensor of claim 12, 7, the thermal conductive film is formed on of any one of Al and Au.

Claim 14. (Original): The absolute humidity sensor of claim 7, further comprising a cap formed over the humidity sensing element and the temperature compensating element to cover the entire surfaces of the humidity sensing element and the temperature compensating element, for separating the humidity sensing element and the temperature compensating element from each other and sealing them therein.

Claim 15 (Original): The absolute humidity sensor of claim 14, a shielding film is formed in a central region of the cap to separate and seal the humidity sensing element and the temperature compensating element.

Claim 16 (Original): The absolute humidity sensor of claim 14, a hole is formed in a region of the cap, where the humidity sensing element is formed, to pass through external humidity.

Claim 17 (Original): The absolute humidity sensor of claim 14, wherein the cap is made of silicon.

Claim 18 (Currently Amended): The absolute humidity sensor of claim 7, further comprising:

a stem joined with a lower portion of the substrate, having pins for electrically connecting with the outside;

a wire for electrically connecting the electrode pads of the humidity sensing element and the temperature compensating element with the pins of the stem; and

a metal shield case formed on an upper portion of the stem to cover an entire surface of the stem including the humidity sensing element and the temperature compensating element.

Claim 19 (Original): The absolute humidity sensor of claim 18, a hole is formed in a region of the stem, where the humidity sensing element is formed, to pass through external humidity.

Claim 20 (Original): The absolute humidity sensor of claim 18, a hole is formed in the shield case to pass through external humidity.